



INTRODUCTION

- Copper is widely used in industry because of its high electrical and thermal conductivity.
- Traditional copper manufacturing produces dense parts but restricts complex internal geometries.
- ADAM (Atomic Diffusion Additive Manufacturing), used on the Markforged Metal X platform, offers a low-cost, powder-free route to printing pure copper with near-net-shape capability.

RESEARCH GAP

- Limited work exists on printed copper, especially regarding its mechanical properties, pore morphology, and microstructural integrity.
- Existing datasets come mostly from manufacturer datasheets rather than independent studies.
- Understanding microstructure and porosity is essential for assessing suitability for high-performance electrical, thermal, and structural applications.

AIM

- To evaluate the mechanical behaviour and microstructural characteristics of copper produced using the ADAM process.

METHODS

1. Print – Debinding - Sintering

- Metal-polymer filament extrusion
- Solvent wash removes core polymer
- Furnace densification

2. Mechanical Testing

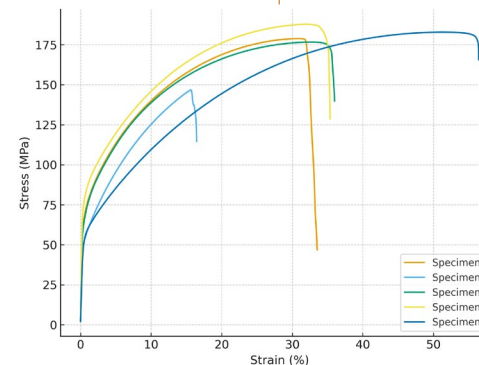
- n = 5 tensile specimens
- Tested according to ASTM E8.
- Print orientation: Solid-XY focusing on primary load-bearing direction in ADAM.

3. Microstructural Analysis

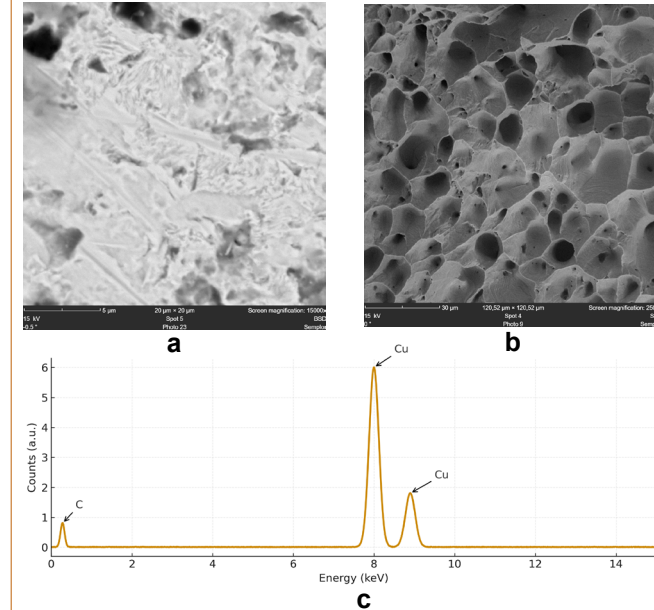
- SEM imaging and EDS mapping.

MECHANICAL PROPERTIES

Property	ADAM Copper
UTS	193 Mpa
YS	26 Mpa
Elongation	35-45%
Rel. Density	96-98%



MICROSTRUCTURE



- a. SEM surface microstructure showing fused copper particles and small isolated pores.
- b. Cross-section SEM image showing larger internal pores typical of ADAM-sintered copper.
- c. EDS confirming Cu with small C/O peaks

CONCLUSION

- ADAM copper achieves near-MIM densities but exhibits anisotropic pore structures, consistent with filament-based ME processes.
- Mechanical strength is primarily limited by sinter-neck development and any residual carbon.
- ADAM is a viable route for complex copper geometries, especially those requiring internal channels or conformal cooling.